

Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

- ◆ -30V, -4.0A, $R_{DS(ON).max}=50m\Omega@V_{GS}=-10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ Green device available

Applications

- ◆ PWM applications
- ◆ Load switch
- ◆ Portable Equipment

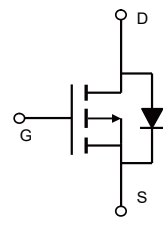
Product Summary

V_{DSS}	-30V
$R_{DS(on).max}@V_{GS}=-10V$	50m Ω
I_D	-4.0A

Pin Configuration



SOT-23-3



Schematic

Absolute Maximum Ratings $T_A = 25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-30	V
Continuous drain current ($T_A = 25^{\circ}C$)	I_D	-4.0	A
Continuous drain current ($T_A = 100^{\circ}C$)		-2.5	A
Pulsed drain current ¹⁾	I_{DM}	-16.0	A
Gate-Source voltage	V_{GSS}	± 12	V
Power Dissipation ($T_A = 25^{\circ}C$)	P_D	1.2	W
Storage Temperature Range	T_{STG}	-55 to +150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to +150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JA}$	104	$^{\circ}C/W$

Package Marking and Ordering Information

Device	Device Package	Marking
VSM3481-S2	SOT-23-3	VSM3481-S2

Electrical Characteristics

 $T_J = 25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0 V, I _D =-250uA	-30	---	---	V
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-0.6	-0.95	-1.3	V
Drain-source leakage current	I _{DSS}	V _{DS} =-30 V, V _{GS} =0 V, T _J = 25°C	---	---	-1	μA
		V _{DS} =-24V, V _{GS} =0 V, T _J = 125°C	---	---	-10	μA
Gate leakage current, Forward	I _{GSSF}	V _{GS} =12 V, V _{DS} =0 V	---	---	100	nA
Gate leakage current, Reverse	I _{GSSR}	V _{GS} =-12 V, V _{DS} =0 V	---	---	-100	nA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} =-10 V, I _D =-4 A	---	41	50	mΩ
		V _{GS} =-4.5 V, I _D =-3.5A	---	47	60	mΩ
		V _{GS} =-2.5 V, I _D =-2.5A		60	85	mΩ
Forward transconductance	g _{fs}	V _{DS} =-5 V , I _D =-4.0A	---	15	---	S
Dynamic characteristics						
Input capacitance	C _{iss}	V _{DS} = -15 V, V _{GS} = 0 V, F = 1MHz	---	1180	---	pF
Output capacitance	C _{oss}		---	80	---	
Reverse transfer capacitance	C _{rss}		---	68	---	
Turn-on delay time	t _{d(on)}	V _{DD} = -15V,V _{GS} =-10V, I _D =-4A Rg=3Ω	---	1.8	---	ns
Rise time	t _r		---	30.2	---	
Turn-off delay time	t _{d(off)}		---	52.5	---	
Fall time	t _f		---	7.3	---	
Gate resistance	R _g	V _{GS} =0V,V _{DS} =0V,f=1MHz	---	11.5	---	Ω
Gate charge characteristics						
Gate to source charge	Q _{gs}	V _{DS} =-15 V, I _D =-4.0A, V _{GS} =-10 V	---	2.1	---	nC
Gate to drain charge	Q _{gd}		---	2.3	---	
Gate charge total	Q _g		---	19.3	---	
Drain-Source diode characteristics and Maximum Ratings						
Continuous Source Current	I _s		---	---	-4.0	A
Pulsed Source Current ⁽²⁾	I _{SM}		---	---	-16.0	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =-2A, T _J =25°C	---	---	-1.2	V

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

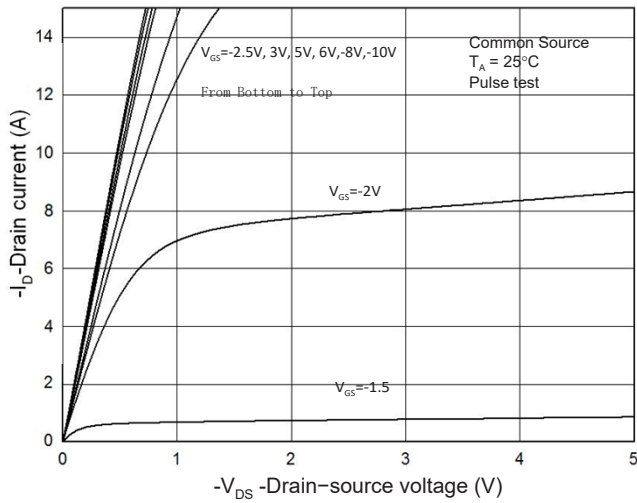


Figure 2. Transfer Characteristics

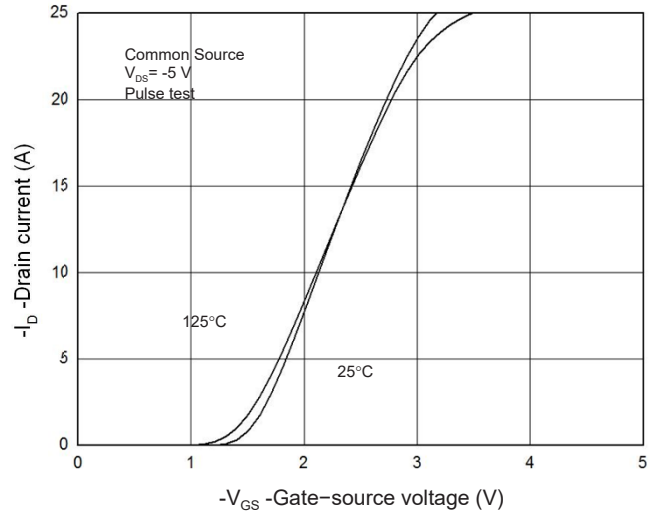


Figure 3. Capacitance Characteristics

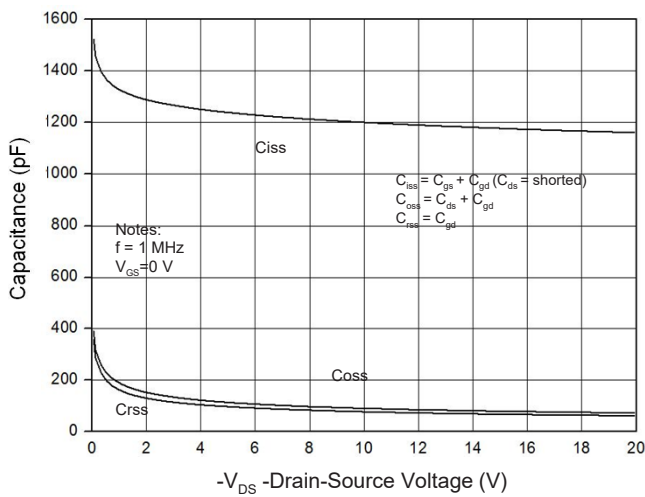


Figure 4. Gate Charge Waveform

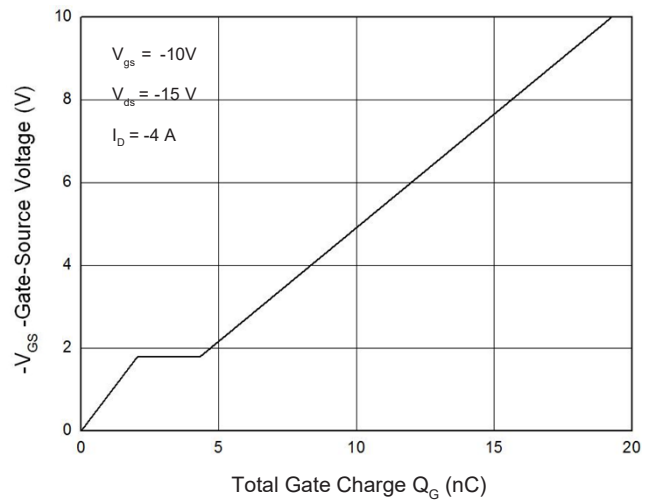


Figure 5. Body-Diode Characteristics

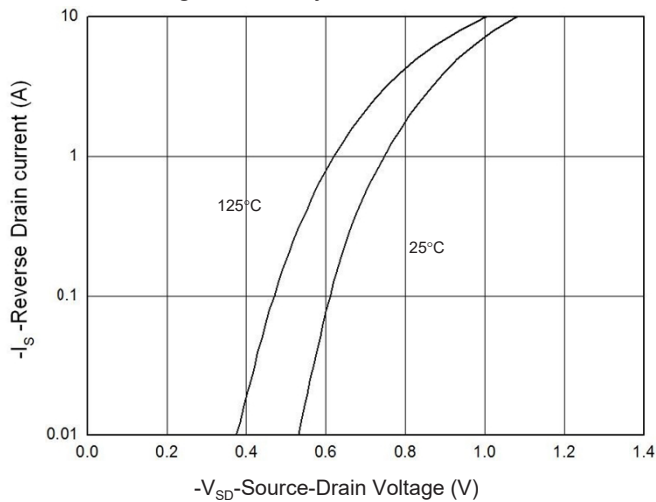


Figure 6. Rdson-Drain Current

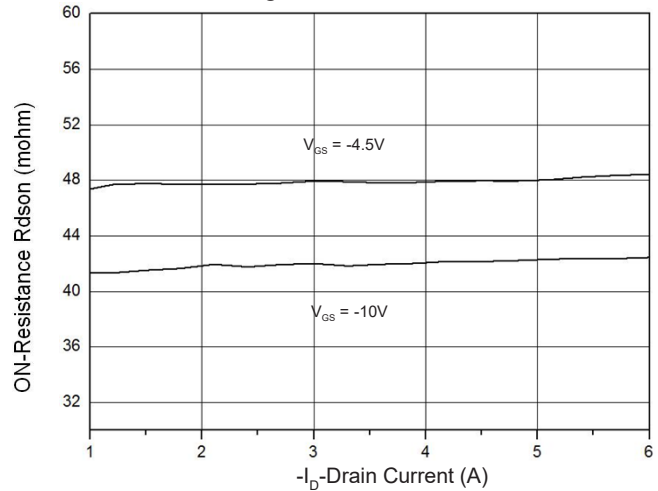


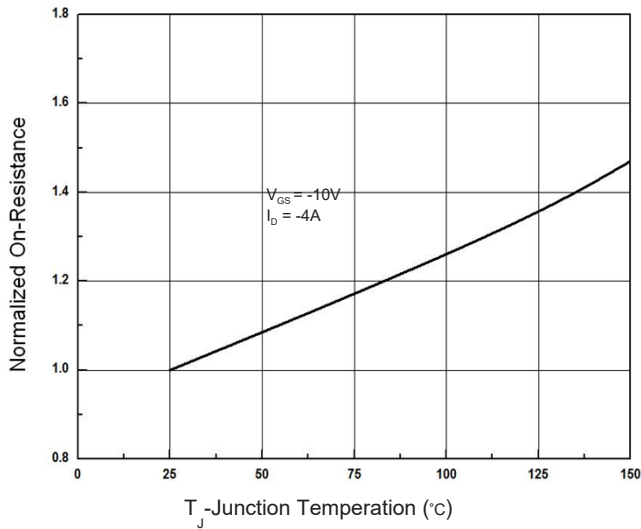
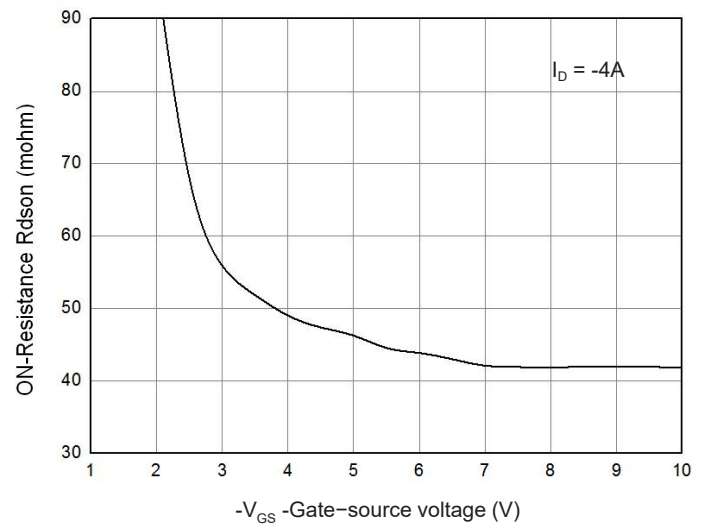
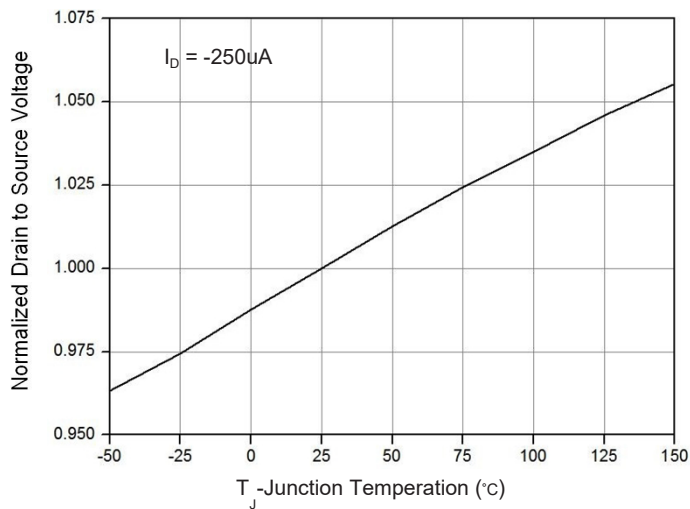
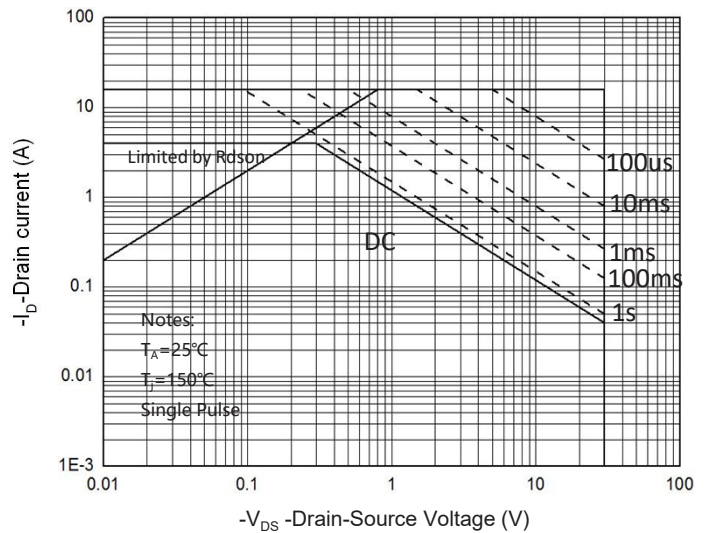
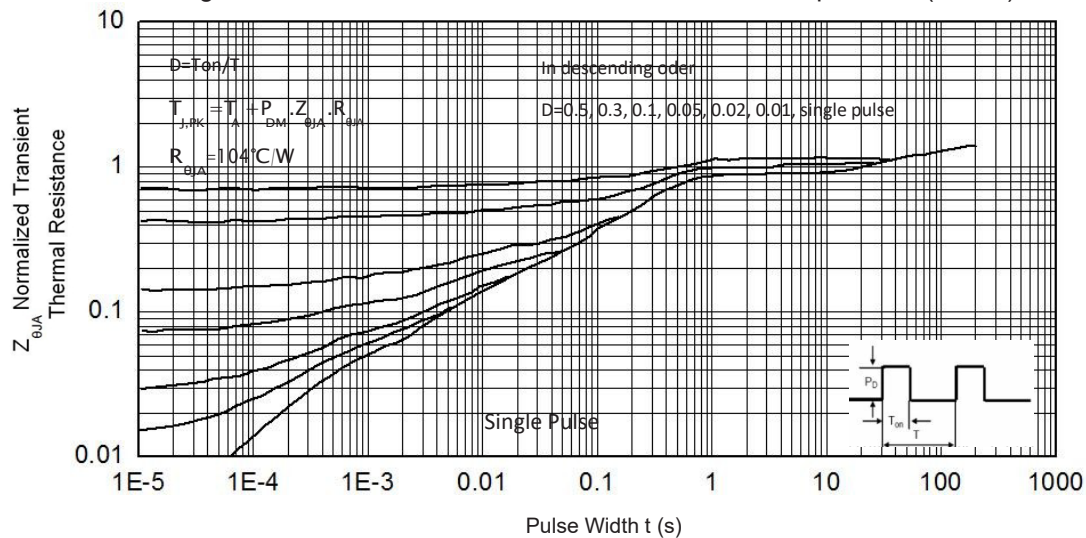
Figure 7. $R_{ds(on)}$ -Junction Temperature($^{\circ}\text{C}$)

Figure 8. $R_{ds(on)}$ vs Gate Voltage

Figure 9. BV_{dss} vs. Junction temperature($^{\circ}\text{C}$)


Figure 10. Maximum Safe Operating Area


Figure 11. Normalized Maximum Transient Thermal Impedance (R_{thJA})


Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

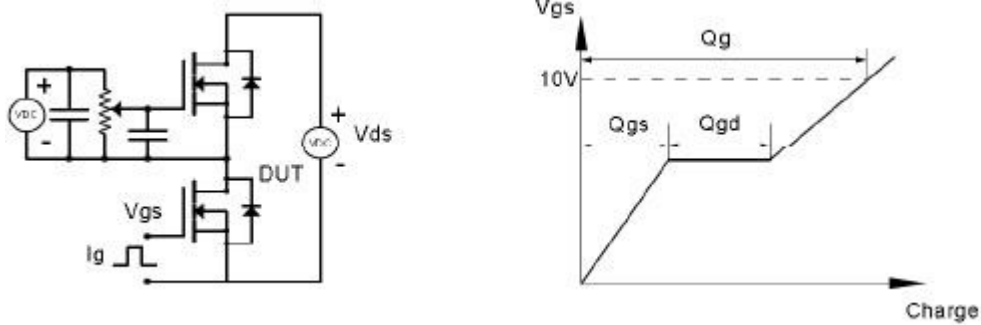


Figure 9. Resistive Switching Test Circuit & Waveforms

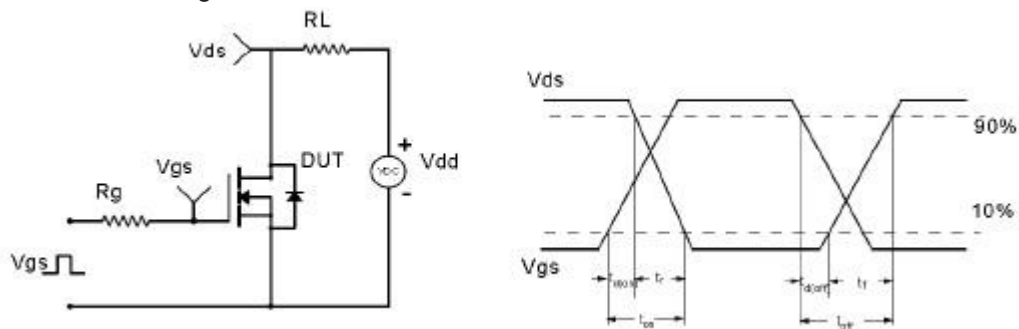


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

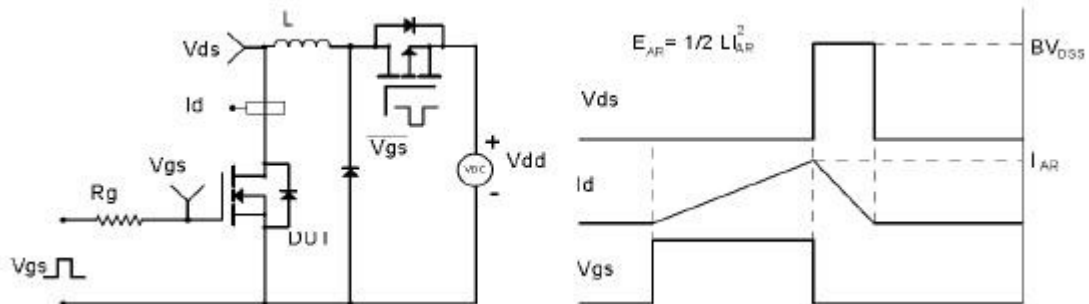


Figure 11. Diode Recovery Circuit & Waveform

